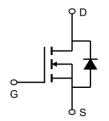


Description

The AP2300AI uses advanced trench technology to provide excellent $R_{\text{DS}(\text{ON})}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a

Battery protection or in other Switching application.



General Features

 $V_{DS} = 20V, I_{D} = 3.3A$

 $R_{DS(ON)} < 60m @ V_{GS} = 2.5V$

 $R_{DS(ON)} < 45m @ V_{GS} = 4.5V$

High power and current handing capability

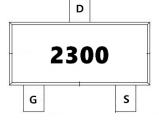
Lead free product is acquired Surface mount package

Application

Battery protection

Load switch

Uninterruptible power supply





Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
AP2300AI	SOT-23	2300	3000

Absolute Maximum Ratings (T_A=25 ℃ unless otherwise noted)

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	20	V	
Gate-Source Voltage	V _G s	±12	V	
Drain Current-Continuous	I _D	3.3	Α	
Drain Current-Pulsed (Note 1)	Ірм	16	Α	
Maximum Power Dissipation	Po	P _D 0.9		
Operating Junction and Storage Temperature Range	Тл,Твтв	-55 To 150	$^{\circ}$ C	
Thermal Resistance,Junction-to-Ambient (Note 2)	Reja	139	°CW	



Electrical Characteristics (T_A=25°Cunless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	20	22	-	V
Zero Gate Voltage Drain Current	Ipss	V _{DS} =20V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	Igss	V _{GS} =±12V,V _{DS} =0V	-	i	±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250μA	0.5	0.75	1.2	V
	Rds(ON)	V _{GS} =2.5V, I _D =2.8A	-	35	60	mΩ
Drain-Source On-State Resistance		V _{GS} =4.5V, I _D =3A	-	29	45	mΩ
Forward Transconductance	g FS	V _{DS} =5V,I _D =3A	-	8	-	S
Input Capacitance	C _{lss}		-	260	-	PF
Output Capacitance	Coss	V _{DS} =10V,V _{GS} =0V,		48	-	PF
Reverse Transfer Capacitance	Crss	F=1.0MHz	-	27	-	PF
Turn-on Delay Time	t _{d(on)}		-	2.5	-	nS
Turn-on Rise Time	t _r	V _{DD} =10V, R _L =3.3Ω	-	3.2	-	nS
Turn-Off Delay Time	td(off)	$V_{GS}=4.5V,R_{GEN}=6\Omega$		21	-	nS
Turn-Off Fall Time	t _f		-	3	-	nS
Total Gate Charge	Qg	V _{DS} =10V,I _D =3A,	-	2.9	5	nC
Gate-Source Charge	Qgs		-	0.4	-	nC
Gate-Drain Charge	Q _{gd}	V _{GS} =4.5V	-	0.6	-	nC
Diode Forward Voltage (Note 3)	VsD	V _{GS} =0V,I _S =3.3A	-	0.75	1.2	V
Diode Forward Current (Note 2)	Is		-	-	3.3	Α

Notes:

- 1、Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, $t \le 10$ sec.
- 3、Pulse Test: Pulse Width ≤ 300 μ s, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production





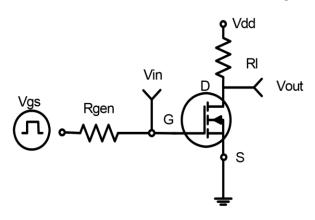


Figure 1:Switching Test Circuit

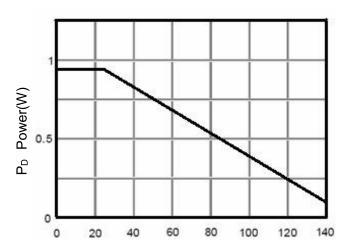


Figure 3 Power Dissipation

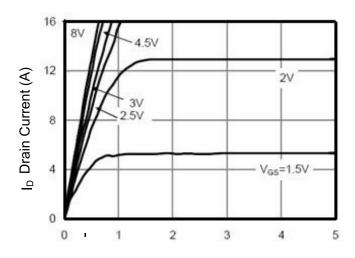


Figure 5: Vds Drain-Source Voltage (V)

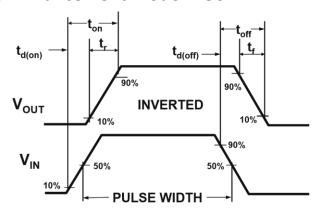


Figure 2:Switching Waveforms

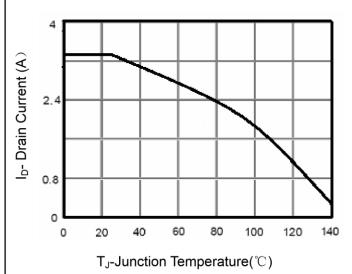


Figure 4 Drain Current

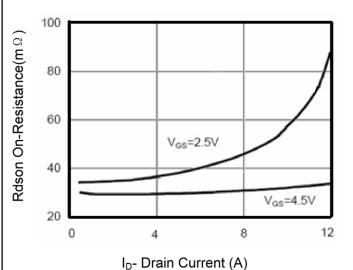
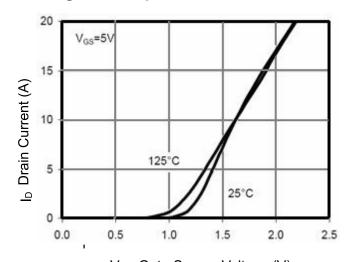


Figure 6 Drain-Source On-Resistance

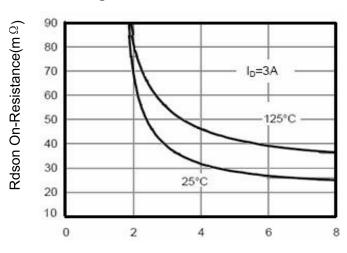




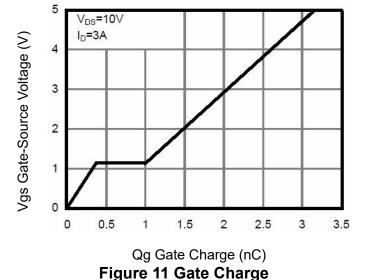
Figure 5 Output Characteristics



Vgs Gate-Source Voltage (V)
Figure 7 Transfer Characteristics



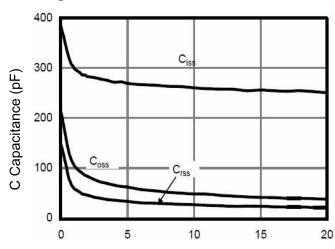
Vgs Gate-Source Voltage (V)
Figure 9 Rdson vs Vgs



0.8 0 25 50 75 100 125 150 175

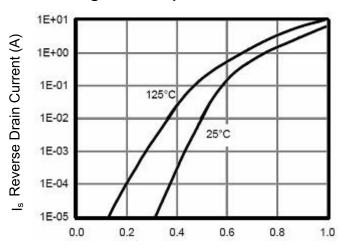
 T_J -Junction Temperature(${}^{\mathbb{C}}$)

Figure 8 Drain-Source On-Resistance



Vds Drain-Source Voltage (V)

Figure 10 Capacitance vs Vds



Vsd Source-Drain Voltage (V)
Figure 12 Source- Drain Diode Forward

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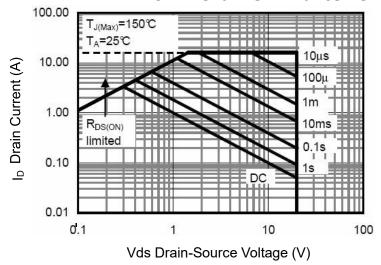
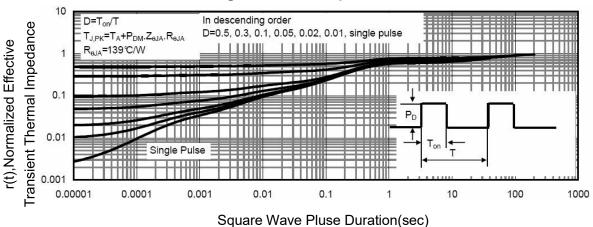


Figure 13 Safe Operation Area

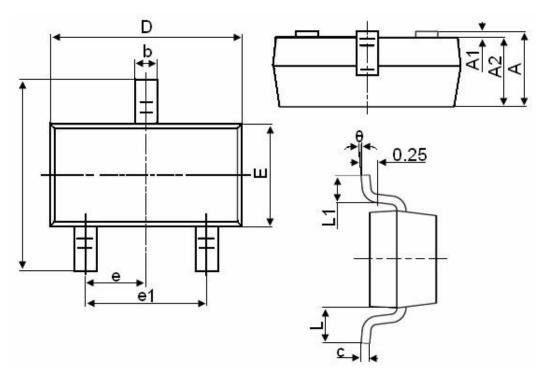


lormalized Maximum Transient Th

Figure 14 Normalized Maximum Transient Thermal Impedance



SOT-23 Package Information



Symbol	Dimensions in Millimeters			
	MIN.	MAX.		
А	0.900	1.150		
A1	0.000	0.100		
A2	0.900	1.050		
b	0.300	0.500		
С	0.080	0.150		
D	2.800	3.000		
E	1.200	1.400		
E1	2.250	2.550		
е		0.950TYP		
e1	1.800	2.000		
L		0.550REF		
L1	0.300	0.500		
θ	0°	8°		





20V N-Channel Enhancement Mode MOSFET Attention

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